

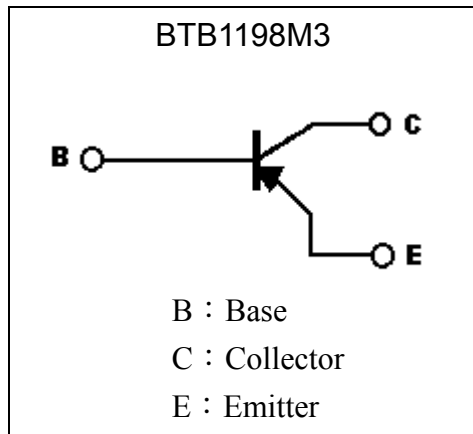
General Purpose PNP Epitaxial Planar Transistor

BTB1198M3

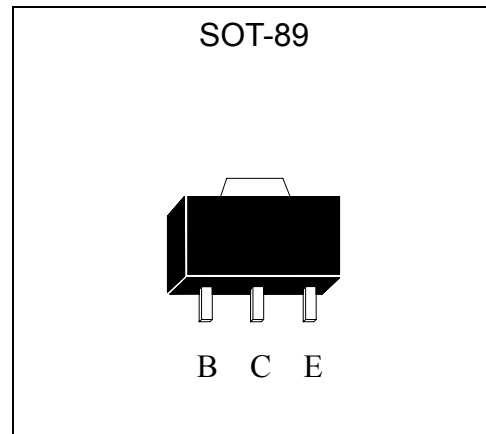
Features

- High breakdown voltage, $BV_{CEO} \geq -100V$
- Large continuous collector current capability
- Low collector saturation voltage
- Complementary to BTD5213M3
- Pb-free lead plating and halogen-free package

Symbol

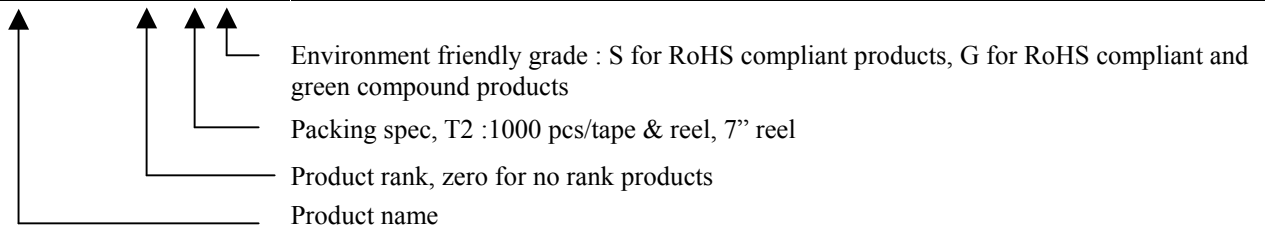


Outline



Ordering Information

Device	Package	Shipping
BTB1198M3-0-T2-G	SOT-89 (Pb-free lead plating and halogen-free package)	1000 pcs / Tape & Reel





Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V _{CB0}	-120	V
Collector-Emitter Voltage	V _{CEO}	-100	
Emitter-Base Voltage	V _{EBO}	-5	
Collector Current(DC)	I _C	-1	A
Collector Current(Pulse)	I _{CP}	-2	
Base Current(DC)	I _B	-200	mA
Power Dissipation	Pd	0.6	W
		1 (Note 1)	
		2 (Note 2)	
Thermal Resistance, Junction to Ambient	R _{θJA}	208	°C/W
		83.3 (Note 1)	
		59.5 (Note 2)	
Operating Junction Temperature Range	T _j	-65~+150	°C
Storage Temperature Range	T _{stg}	-65~+150	°C

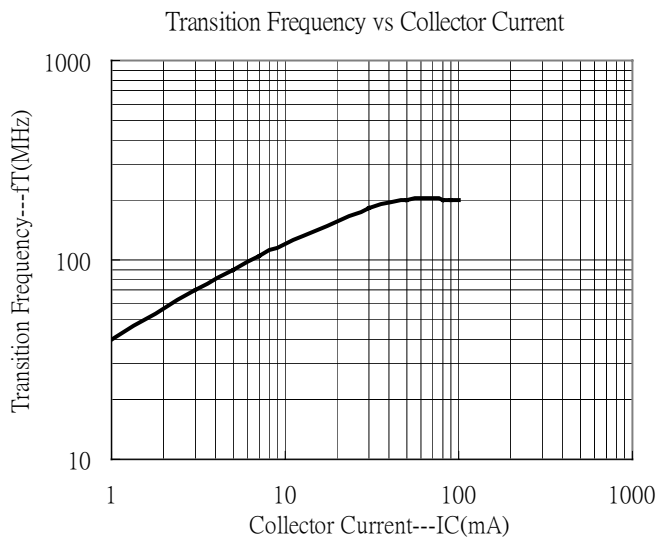
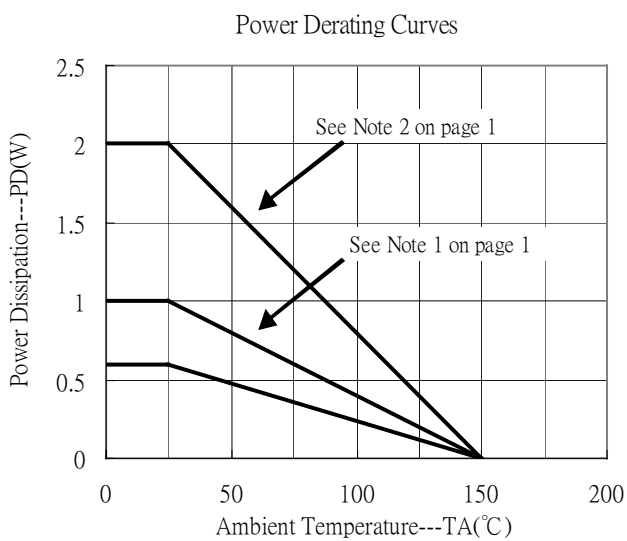
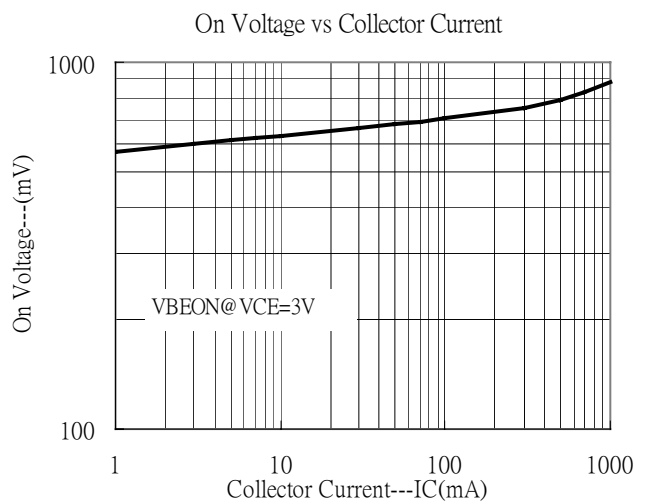
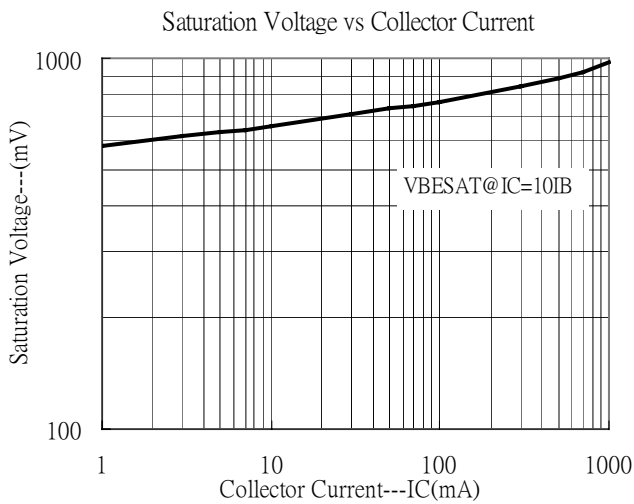
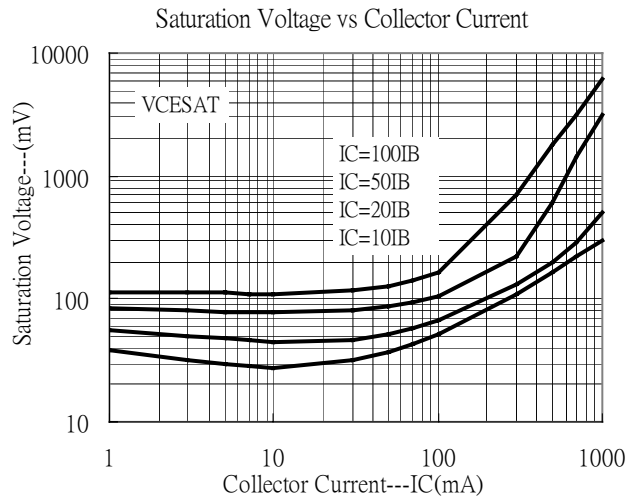
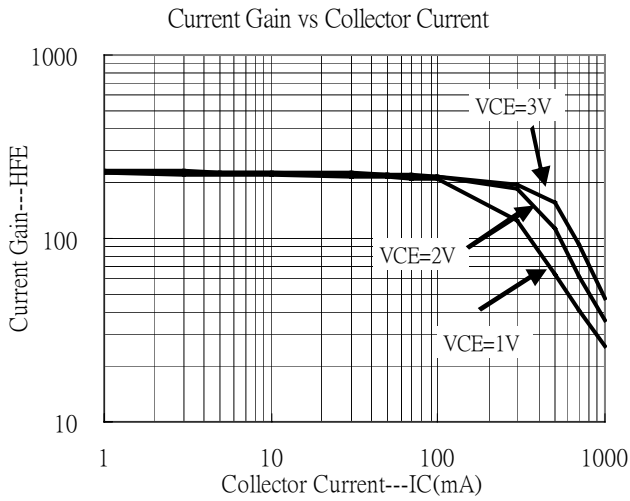
Note : 1. When mounted on FR-4 PCB with area measuring 10×10×1 mm
 2 . When mounted on ceramic with area measuring 40×40×1 mm

Characteristics (Ta=25°C)

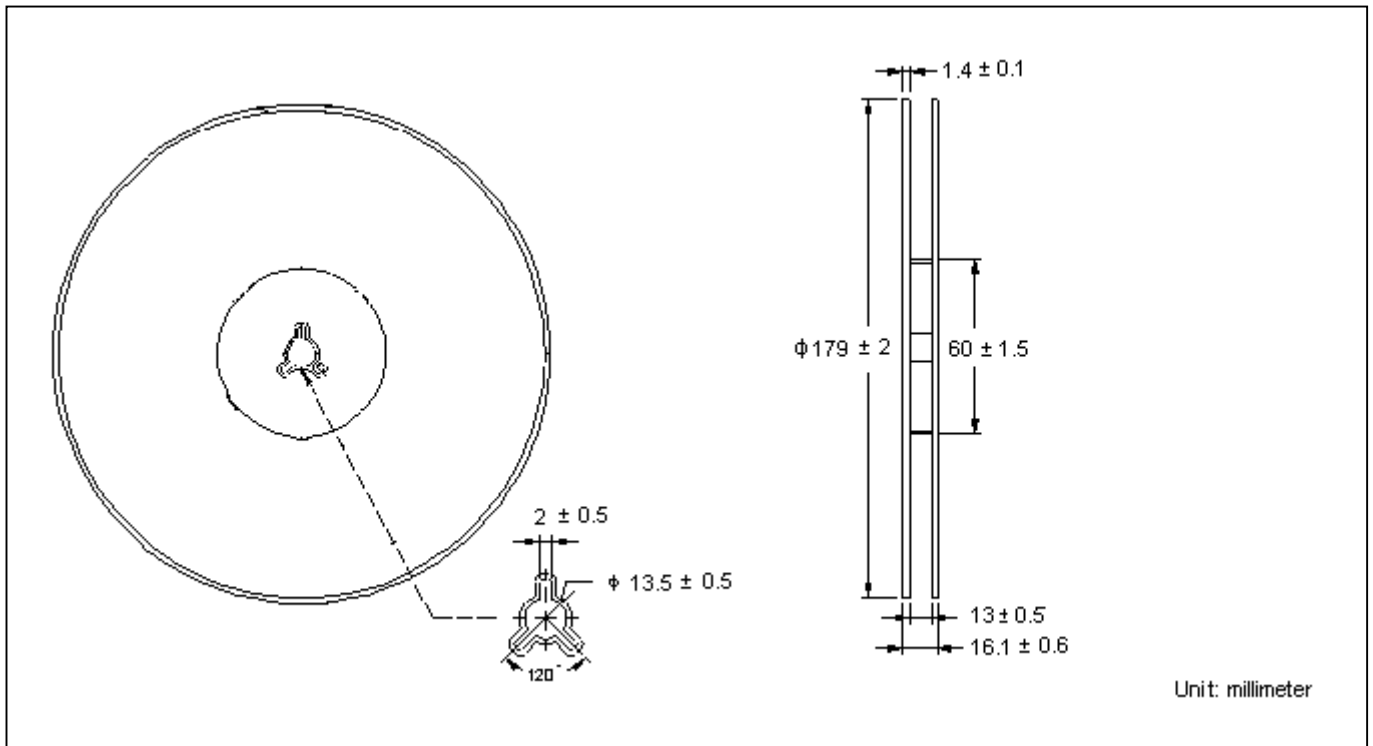
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CB0}	-120	-	-	V	I _C =-100μA
BV _{CEO}	-100	-	-	V	I _C =-10mA
BV _{EBO}	-5	-	-	V	I _E =-100μA
I _{CB0}	-	-	-100	nA	V _{CB} =-100V
I _{EBO}	-	-	-20	nA	V _{EB} =-4V
*V _{CE(sat)}	-	-0.1	-0.2	V	I _C =-250mA, I _B =-25mA
*V _{CE(sat)}	-	-0.16	-0.3	V	I _C =-500mA, I _B =-50mA
*V _{CE(sat)}	-	-0.3	-0.5	V	I _C =-1A, I _B =-100mA
*V _{BE(sat)}	-	-0.89	-1.1	V	I _C =-500mA, I _B =-50mA
*V _{BE(on)}	-	-	-1	V	V _{CE} =-5V, I _C =-1mA
*h _{FE} 1	160	-	-	-	V _{CE} =-2V, I _C =-5mA
*h _{FE} 2	180	-	390	-	V _{CE} =-2V, I _C =-150mA
*h _{FE} 3	40	-	-	-	V _{CE} =-2V, I _C =-500mA
f _T	150	200	-	MHz	V _{CE} =-10V, I _C =-50mA, f=100MHz
Cob	-	11	15	pF	V _{CB} =-10V, I _E =0A, f=1MHz

*Pulse Test: Pulse Width ≤380μs, Duty Cycle≤2%

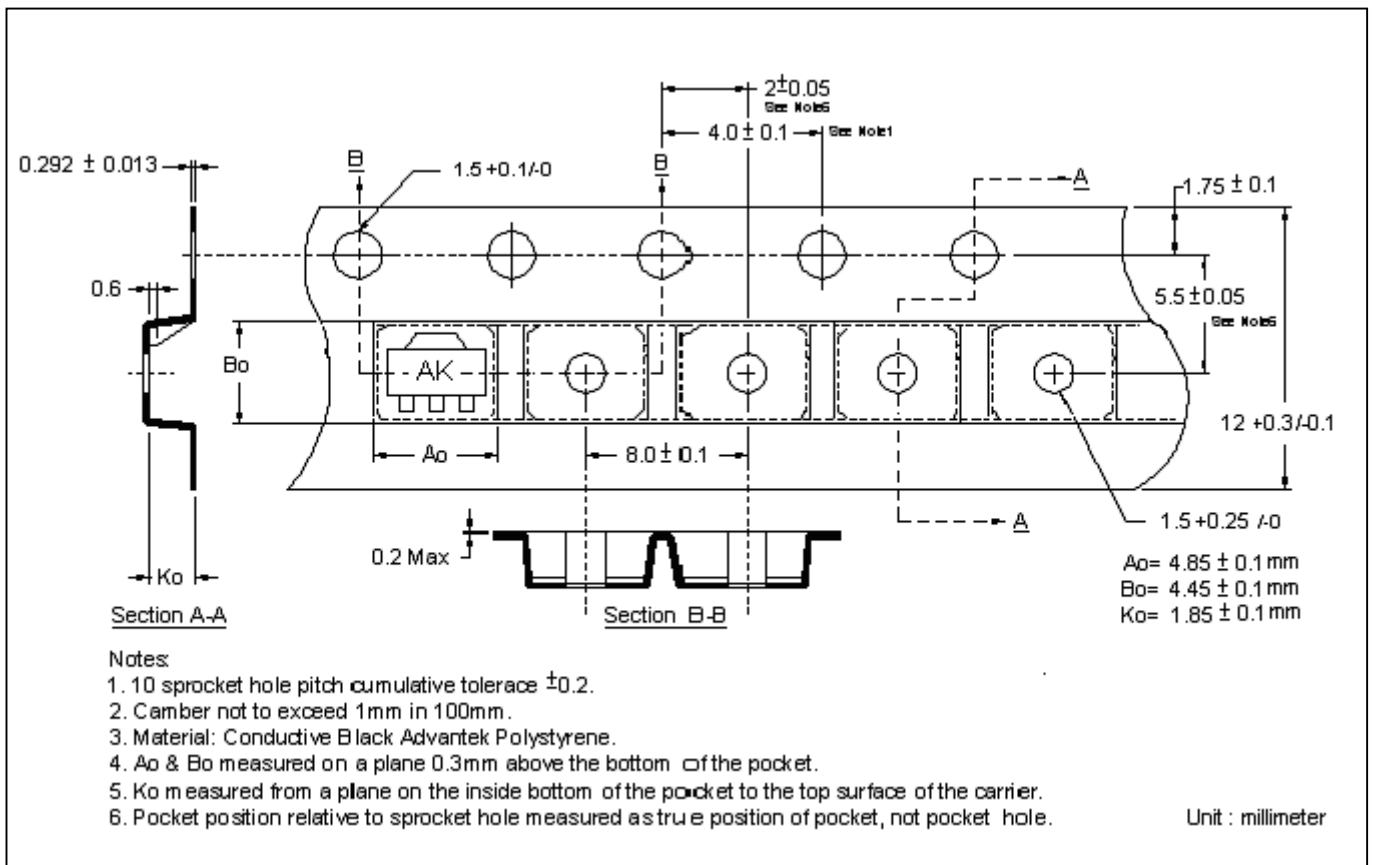
Typical Characteristics



Reel Dimension

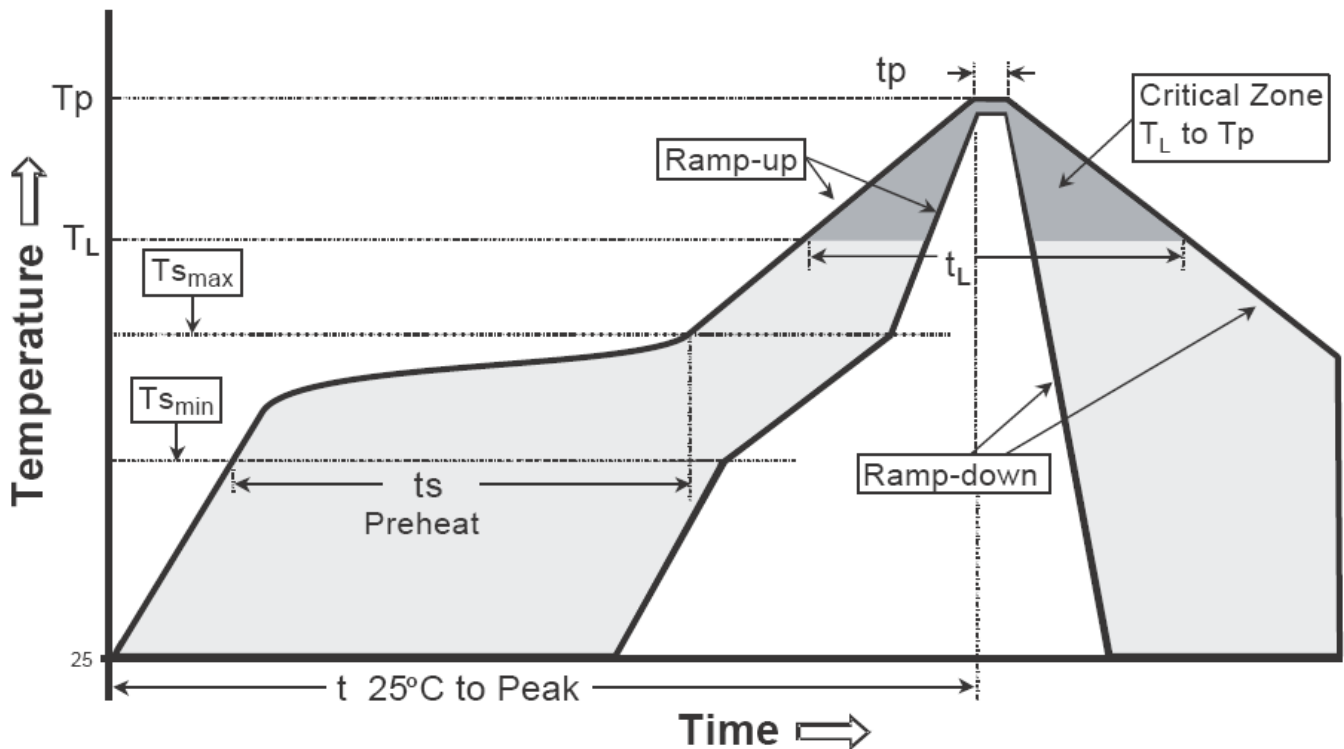


Carrier Tape Dimension



Recommended wave soldering condition

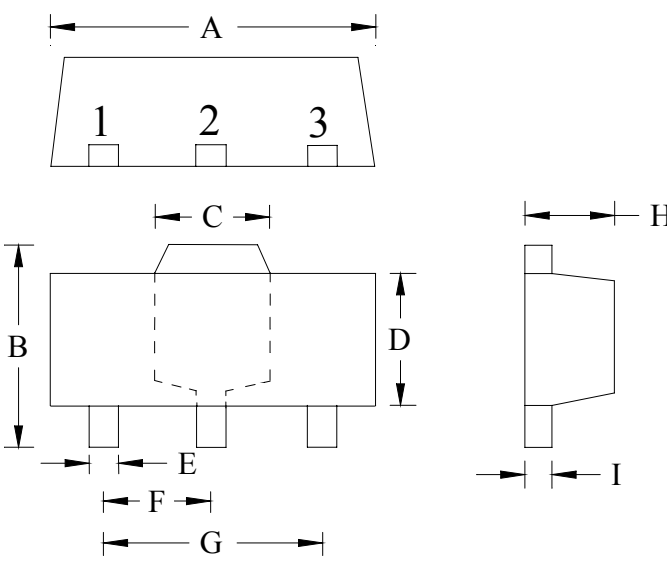
Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow


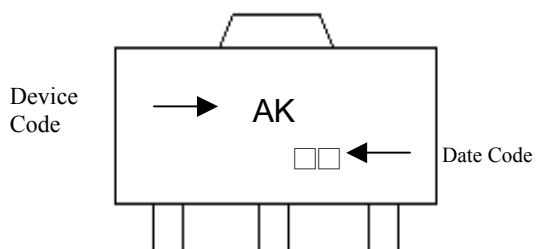
Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(T _{s min})	100°C	150°C
-Temperature Max(T _{s max})	150°C	200°C
-Time(t _{s min} to t _{s max})	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T _L)	183°C	217°C
- Time (t _L)	60-150 seconds	60-150 seconds
Peak Temperature(T _p)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOT-89 Dimension



Marking:



Device Code → **AK** ← Date Code

Style: Pin 1. Base 2. Collector 3. Emitter

3-Lead SOT-89 Plastic
 Surface Mounted Package
 CYStek Package Code: M3

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0591	TYP	1.50	TYP
B	0.1551	0.1673	3.94	4.25	G	0.1181	TYP	3.00	TYP
C	0.0610	REF	1.55	REF	H	0.0551	0.0630	1.40	1.60
D	0.0906	0.1024	2.30	2.60	I	0.0138	0.0173	0.35	0.44
E	0.0126	0.0205	0.32	0.52					

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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